

**Features**

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC



SMB (DO - 214AA)

Mechanical Date

- **Case:** JEDEC DO-214AA molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end

Major Ratings and Characteristics

$I_{F(AV)}$	2.0A
V_{RRM}	20 V to 100 V
I_{FSM}	50A
V_F	0.50V, 0.55V, 0.70V, 0.85V
$T_j \text{ max.}$	125 °C

Maximum Ratings & Thermal Characteristics(T_A = 25 °C unless otherwise noted)

Items	Symbol	SK22	SK23	SK24	SK25	SK26	SK28	SK210	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	V
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	V
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	V
Maximum average forward rectified current	$I_{F(AV)}$	2.0							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	50							A
Voltage rate of change (rated V_R)	dv/dt	10000							V/μs
Thermal resistance from junction to lead ⁽¹⁾	$R_{θJL}$	25							°C/W
Operating junction and storage temperature range	T_J, T_{STG}	-65 to +125							°C

Note 1: Mounted on P.C.B. with 0.28 x 0.28" (7.0 x 7.0mm) copper pad areas.

Electrical Characteristics (T_A = 25 °C unless otherwise noted)

Items	Test conditions	Symbol	SK22	SK23~24	SK25~26	SK28~210	UNIT	
Instantaneous forward voltage	$I_F=2.0A^{(2)}$	V_F	0.50	0.55	0.70	0.85	V	
Reverse current	$V_R=V_{DC}$	I_R	$T_A=25^\circ C$				0.5	mA
			$T_A=100^\circ C$				5	

Note 2: Pulse test:300μs pulse width,1% duty cycle.



SK22~SK210 Surface Mount Schottky Rectifiers

Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

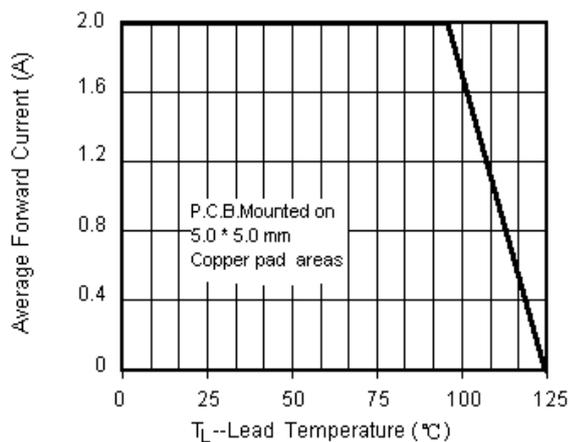


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

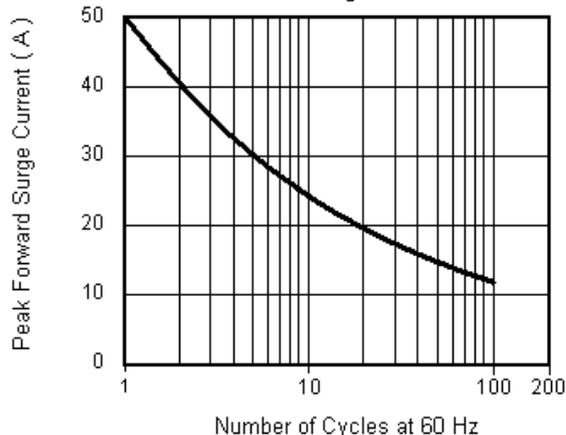


Fig.3 Typical Instantaneous Forward Characteristics

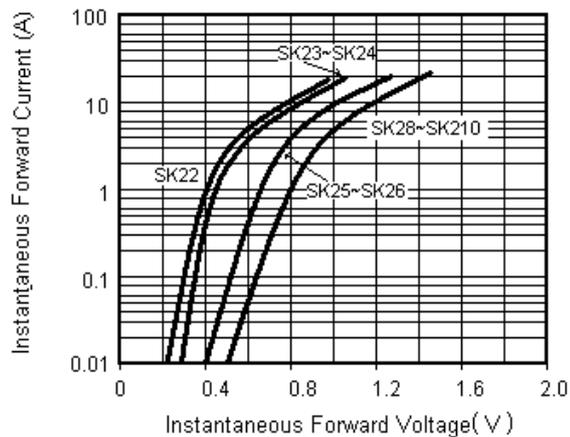
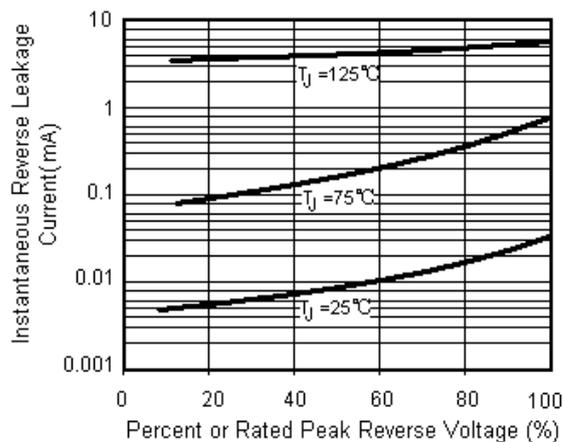
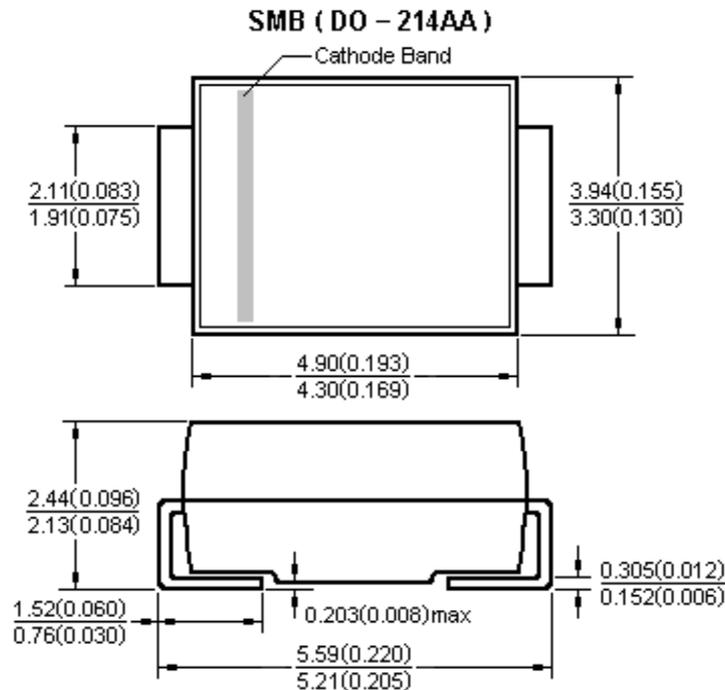


Fig.4 Typical Reverse Leakage Characteristics





Package Outline



Dimensions in millimeters and (inches)

Notice

- Product is intended for use in general electronics applications.
- Product should be worked less than the ratings; if exceeded, may cause permanent damage or introduce latent failure mechanisms.
- The absolute maximum ratings are rated values and must not be exceeded during operation. The following are the general derating methods you design a circuit with a device.
 - $I_{F(AV)}$: We recommend that the worst case current be no greater than 80% .
 - I_{FSM} : This rating specifies the non-repetitive peak current. This is only applied for an abnormal operation, which the general during the lifespan of the device.
 - T_J : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a T_J of below 125°C.

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